

Title (en)

ALUMINIUM PASTES FOR THICK FILM HYBRIDES

Title (de)

ALUMINIUMPASTE FÜR DICKFILMHYBRIDE

Title (fr)

PÂTE À L'ALUMINIUM POUR CIRCUITS HYBRIDES À COUCHES ÉPAISSES

Publication

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Application

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Abstract (en)

[origin: WO2015162298A1] The invention relates to aluminum-containing metallisation pastes for producing hybrid circuits on ceramic substrates.

IPC 8 full level

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